## DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

DOCKET NO. **TS2001-413** 

As a below named Inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled Novel Method To Improve Bump Reliability For Flip Chip Device

the specification of which (check one)	•		
X is attached hereto.			
was filed on	***************************************		•
Application Serial No.			
and was amended on(if a	nnligable)		
I hereby state that I have reviewed and u amended by any amendment referred to	inderstand the contents of the ab	ove Identified specification including the claim	ms, as
I acknowledge the duty to disclose infor 37, Code of Federal Regulations, §1.56(	mation which is material to the ea.	examination of this application in accordance v	with Title
a filing date before that of the applicatio	nder Title 35, United States Coo ave also identified below any for n on which priority is claimed:	te §119 of any foreign application(s) for pater eign application for patent or inventor's certific	nt or cate having
Prior Foreign Application(s)		Priority Claimed:	
(Number)		•	
	(Country)	(Day/Month/Year Filed)	٠
(Number)	(Country)	(Day/Month/Year Filed)	
I hereby claim the benefit under Title 35 as the subject matter of each of the clair provided by the first paragraph of Title defined in Title 37, Code of Federal Regnational or PCT international filing date	i, United States Code §120 of arms of this application is not discled. United States Code, §112, 1 gulations, §1.56(a) which occurred this application:	by United States application(s) listed below an osed in the prior United States application in the acknowledge the duty to disclose material infect between the filing date of the prior application.	d, insofar the manner formation as tion and the
(Application Serial No.)	(Filing Date) (Status)	(patented, pending, abandoned)	
I hereby declare that all statements mad belief are believed to be true; and furthe the like so made are punishable by fine of that such willful false statements may je	e herein of my own knowledge a er that these statements were ma or imprisonment, or both, under opardize the validity of the appli	tre true and that all statements made on inform the with the knowledge that willful false statem Section 1001 of Title 18 of the United States cation or any patent issued thereon.	nation and nents and Code and
POWER OF ATTORNEY: As a named application and transact all business in t	inventor, I hereby appoint the f he Patent and Trademark Office	ollowing attorney(s) and/or agent(s) to prosect connected therewith. (list name & registration	cute this n no.)
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